

**8 Leads - UTDFN
Package Material Declaration**



Date	22-Feb-19	Product name	Integrated Circuit
Package Code	LD	RoHS Compliant	Y
Package Name	Ultra Thin Leadframe Package Double	Halogen Free	Y
Product Total Mass (g)	0.0063	Plating	NiPdAu
Product Number	MLX90297		

Material Declaration

Part Name	Material Name	Component Weight (g)	Material Component (Element)	CAS #	Element ratio (%)	Material Weight (g)	Ratio total Wt (ppm)
Leadframe	Copper Alloy C7025, NiPdAu plated	0.0028	Cu (remaining)	7440-50-8	94.65	0.00267	424885
			Si (0.25~1.2%)	7440-21-3	0.52	0.00001	2334
			Ni (2.2~4.2%)	7440-02-0	3.43	0.00010	15397
			Mg (0.05~0.3%)	7439-95-4	0.13	0.000004	584
			Ni plating (0.8~1.5%)	7440-02-0	1.15	0.00003	5162
			Pd (0.05~0.15%)	7440-05-3	0.1	0.000003	449
			Au (0.01~0.02%)	7440-57-5	0.020	0.0000006	90
Die	Silicon	0.0003	Silicon (Si)	7440-21-3	99.99	0.00034	54117
			others	-	0.01	0.0000000	5
Die attach material	Conductive epoxy QMI519	0.0002	Silver (Ag)	7440-22-4	80	0.00012	19102
			Acrylic resin (Compound of a polymeric network)	none	19.98	0.00003	4771
			others	-	0.02	0.000000	5
Wire	Gold	0.00002	Gold (Au)	7440-57-5	99	0.00002	3467
			Palladium (Pd)	7440-05-3	1	0.00000022	35
Encapsulation	Epoxy Resin EMEG770HCD	0.0030	Silica fused (85~95%)	60676-86-0	93.7	0.00276	440011
			Epoxy Resin (1~5%)	Proprietary	3	0.00009	14088
			Phenol Resin (1~5%)	Proprietary	3	0.00009	14088
			Carbon black (0.1~0.5%)	1333-86-4	0.3	0.00001	1409

Total package weight (g) 0.0063

Comments

- Composition derived from MSDS and material CoC from vendors
- Component weight based on assembly of generic parts
- Reliability qualification reports are available upon request through the appropriate sales or marketing contact
- Third party testing for RoHS substances are available upon request to environment@melexis.com

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